

Electronic Patent Application Fee Transmittal

Application Number:	10829479			
Filing Date:	22-Apr-2004			
Title of Invention:	Multilayer printed wiring board and its manufacturing method, and resin composition for filling through-hole			
First Named Inventor/Applicant Name:	Motoo Asai			
Filer:	Marvin Jay Spivak/Sachie Fazzone			
Attorney Docket Number:	251496US90RE			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180